2017 CMPUG SPRING MEETING – FINAL AGENDA

Topic: Advances in CMP Consumables, Materials and Tools

Meeting Date: April 13, 2017

Time: 12:00 pm - 6:00 pm

Location: Embassy Suites Downtown Portland
319 SW Pine Street
Portland, Oregon 97204

Parking: Located at the hotel or nearby parking structures

FREE CONFERENCE REGISTRATION
Click for Online Registration

Speakers/Agenda listed below

Chair (Co-Chair):
Michael Pevny, 3M, mpevny@mmm.com
Jeff McKinnis, Fujimi, jmckinnis@fujimico.com

The Chemical Mechanical Planarization Users Group (CMPUG) Symposium on Advances in CMP Consumables, Materials and Tools commences on April 13, 2017. The symposium will provide an international forum for academic researchers, industrial practitioners and engineers from around the world for the exchange of information on state-of-the-art research in CMP semiconductor technology. The CMPUG promotes the exchange of opportunities, ideas, friendly relationships and research collaboration. The areas of focus for this meeting will be the following:

- CMP consumables and materials
- CMP Polishing and Metrology Tools
- CMP Process Integration

SPEAKERS/AGENDA

12:30 pm – Registration/Badge Pick up at entrance to Queen Marie Ballroom inside the Embassy Suites

12:50 pm – Welcome and Acknowledgment of sponsors; by conf co-chairs Michael Pevny (3M) and Jeff McKinnis (Fujimi)

1:00 pm – High Rate Acidic Slurries, Julia Kozhukh, Dow

1:25 pm – Holographic Characterization of Agglomerates, Fook Cheong, Spheryx

1:50 pm – Stribeck Curve Improvements for Cu and WCMP on Soft Pads, Ara Philipossian, University of Arizona and Araca Inc.

2:20 pm – Enhanced Material Removal Rate for III/V Semiconductors, Bahar Basim, and Sebnem Ozbek, Ozyegin University

2:45 pm – Awards/Recognition; Dr. Babu
2:55 pm – Coffee Break/Poster Session/Networking

3:30 pm – CMP of Divinylsiloxane-bis-benzocyclobutene (DVS-BCB or BCB) low-k ILD Polymer, Zenon Carlos, Hughes Research Labs.

3:55 pm – Bulk Cu CMP: Development and challenges of high removal rate, low topography slurries, James McDonough, Fujifilm Planar Solutions LLC

4:20 pm – High Performance Pad Conditioning (HPPC) Arm for Advanced Pad Conditioning, Raghava Kakireddy, Applied Materials

4:45 pm – The Impact of Sample Containers on Large Particle Count for CMP slurries, Brian Kim, Fujimi Corporation

5:10 pm – ICPT Announcement

5:15 pm – Concluding remarks by conf co-chairs Michael Pevny (3M) and Jeff McKinnis (Fujimi)

5:20 pm – Hors d’oeuvre served with cash bar

6:00 pm – Meeting adjourn

All presentations will be posted on the CMPUG Proceedings webpage following the meeting.

If you would like to sponsor this meeting or list a banner ad on the User Group website, please check out our “NCCAVS Marketing/ Sponsorship” opportunities at: NCCAVS_marketing_opportunities